

1.6X0.8mm SMD CHIP LED LAMP

Hyper Red Part Number: APH1608SURCK

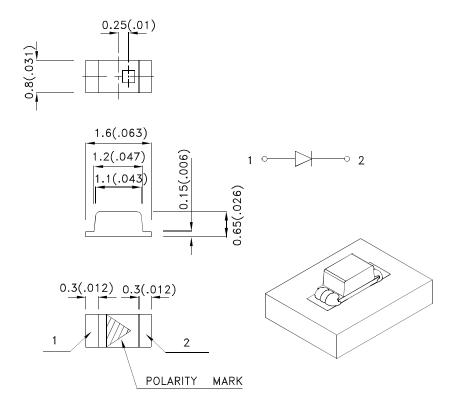
Features

- 1.6mmX0.8mm SMT LED, 0.65mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		2.	Min.	Тур.	201/2
APH1608SURCK	Hyper Red (AlGaInP)	WATER CLEAR	70	220	120°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	630		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA
С	Capacitance	Hyper Red	35		pF	V _F =0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	1.95	2.5	V	IF=20mA
lr	Reverse Current	Hyper Red		10	uA	V _R =5V

Notes:

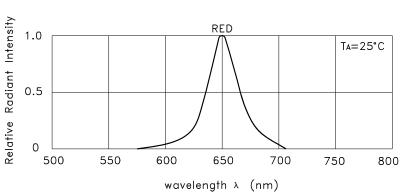
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	185	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

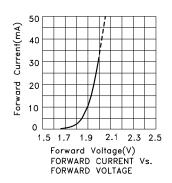
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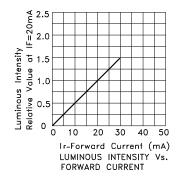


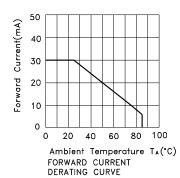
RELATIVE INTENSITY Vs. WAVELENGTH

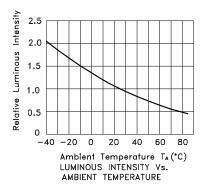
Hyper Red

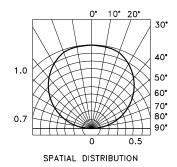
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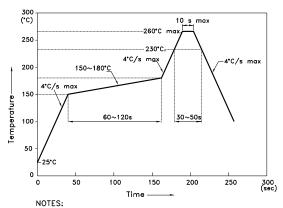
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

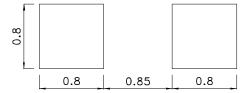
Reflow Soldering Profile For Lead-free SMT Process.



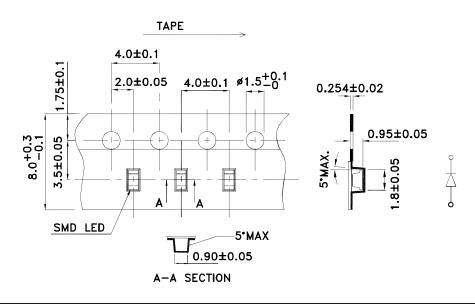
1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

3.Number of reflow process shall be 2 times or less.

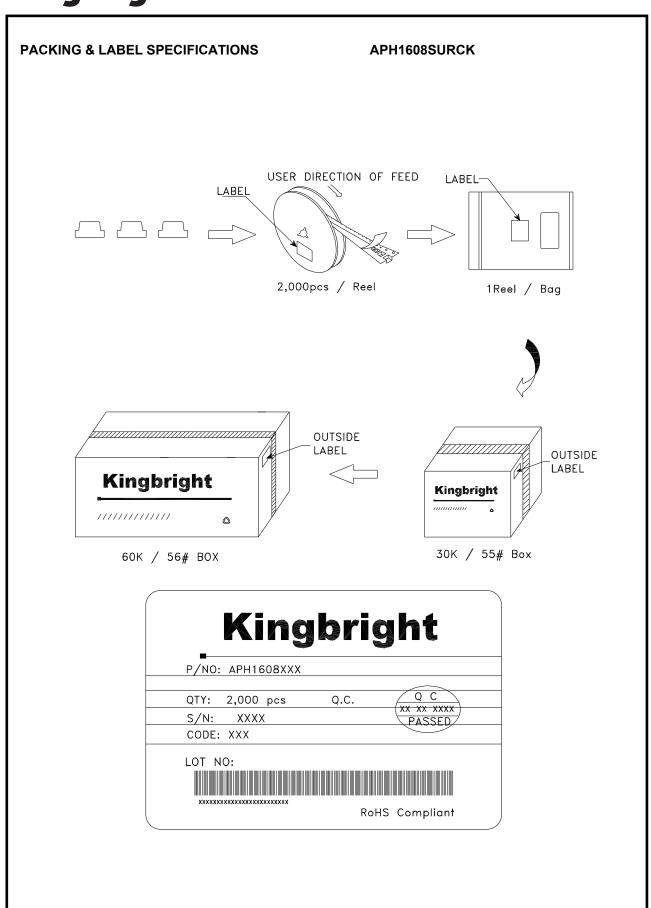
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units : mm)



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